## INTEGRATED CIRCUITS



Product specification

1997 May 23





### SA2420

#### DESCRIPTION

The SA2420 transceiver is a combined low-noise amplifier, receive mixer, transmit mixer and LO buffer IC designed for high-performance low-power communication systems for 2.4-2.5GHz applications. The LNA has a 2.5dB noise figure at 2.45GHz with 14dB gain and an IP3 intercept of -3dBm at the input. The gain is stabilized by on-chip compensation to vary less than ±0.2dB over the -40 to +85°C temperature range. The wide-dynamic-range receive mixer has a 10.9dB noise figure and an input IP3 of +2.8dBm at 2.45GHz. The nominal current drawn from a single 3V supply is 37mA in transmit mode and 22mA in receive mode.

#### **FEATURES**

- Low current consumption: 37mA nominal transmit mode and 22mA nominal receive mode
- Fabricated on a high volume, rugged BiCMOS technology
- High system power gain: 22.5dB (LNA + Mixer) at 2.45GHz
- TSSOP24 package
- Excellent gain stability versus temperature and supply voltage
- -10dBm LO input power can be used to drive the mixer
- Operates with either full or half frequency LO
- Wide IF range: 50-500MHz

ORDERING INFORMATION					
DESCRIPTION	TEMPERATURE RANGE	ORDER CODE	DWG #		
24-Pin Plastic Thin Shrink Small Outline Package (Surface-mount, TSSOP)	-40 to +85°C	SA2420DH	SOT355-1		

#### **BLOCK DIAGRAM**



Figure 2. SA2420 Block Diagram

#### **PIN CONFIGURATION**



Figure 1. Pin Configuration

#### **APPLICATIONS**

2.45GHz WLAN front-end (802.11, ISM)

SA2420

### **ABSOLUTE MAXIMUM RATINGS**

SYMBOL	PARAMETER	RATING	UNITS
V <sub>CC</sub>	Supply voltage	-0.3 to +6	V
V <sub>IN</sub>	Voltage applied to any pin	-0.3 to (V <sub>CC</sub> + 0.3)	V
PD	Power dissipation, T <sub>A</sub> = 25°C (still air) 24-Pin Plastic TSSOP	555	mW
T <sub>JMAX</sub>	Maximum operating junction temperature	150	°C
P <sub>MAX</sub>	Maximum power (RF/IF/LO pins)	+20	dBm
T <sub>STG</sub>	Storage temperature range	-65 to +150	°C

NOTE:

Transients exceeding these conditions may damage the product.
Maximum dissipation is determined by the operating ambient temperature and the thermal resistance, and absolute maximum ratings may

impact product reliability θ<sub>JA</sub>: 24-Pin TSSOP = 117°C/W
IC is protected for ESD voltages for 2000V, excepts pins 10 and 12, which are protected up to 500V.

#### **RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER	RATING	UNITS
V <sub>CC</sub>	Supply voltage	2.7 to 5.5	V
T <sub>A</sub>	Operating ambient temperature range	-40 to +85	°C
TJ	Operating junction temperature	-40 to +105	°C

#### DC ELECTRICAL CHARACTERISTICS

 $V_{CC}$  = +3V,  $T_A$  = 25°C; unless otherwise stated.

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS					UNITS	
STWBOL	FARAMETER	TEST CONDITIONS	MIN	<b>-4</b> σ	ТҮР	<b>+4</b> σ	MAX	01113	
Ісстх	Supply current, Transmit	LO mode = Hi	25		37		45	mA	
ICCRX	Supply current, Receive	LO mode = Hi	15		22		28	mA	
ICC OFF	Power down mode (Tx/Rx SW = Low)	LO mode = Hi, LNA gain = Hi			0		10	μA	
V <sub>LNA-IN</sub>	LNA input voltage	Receive mode			0.855			V	
I <sub>LNA-OUT</sub>	LNA output bias current	Receive mode			4.0			mA	
V <sub>LO 2.1 GHz</sub>	LO buffer DC input voltage	LO mode = Hi			2.1			V	
V <sub>LO 1.05 GHz</sub>	LO buffer DC input voltage	LO mode = Low			2.1			V	
V <sub>TX IF</sub>	Tx Mixer input voltage	Transmit mode			1.7			V	
V <sub>TX IFB</sub>	Tx Mixer input voltage	Transmit mode			1.7			V	

SA2420

# Low voltage RF transceiver — 2.45 GHz

AC ELECTRICAL CHARACTERISTICS

 $V_{CC}$  = +3V,  $\ T_A$  = 25°C;  $LO_{IN}$  = -10dBm @ 2.1GHz;  $f_{RF}$  = 2.45GHz; unless otherwise stated.

CVMDOI	DADAMETED	TEAT AGNIDITIONS	LIMITS					
SYMBOL	PARAMETER	TEST CONDITIONS	MIN	<b>-4</b> σ	ТҮР	<b>+4</b> σ	MAX	UNITS
Low Noise	Amplifier (In = Pin 2; Out = 23)		1					
S <sub>21</sub>	Amplifier gain	LNA gain = Hi		12.7	14.0	15.3		dB
$\Delta S_{21}/\Delta T$	Gain temperature sensitivity	LNA gain = Hi			-0.002			dB/°C
$\Delta S_{21}/\Delta V_{CC}$	Gain V <sub>CC</sub> drift	LNA gain = Hi			0.3			dB/V
S <sub>12</sub>	Amplifier reverse isolation	LNA gain = Hi			-22			dB
S <sub>11</sub>	Amplifier input match <sup>1</sup>	LNA gain = Hi			-8			dB
S <sub>22</sub>	Amplifier output match <sup>1</sup>	LNA gain = Hi			-8			dB
ISO	Isolation: LO <sub>1</sub> to LNA <sub>IN</sub>	LO mode = Hi, LNA gain = Hi			-45			dB
P <sub>-1dB</sub>	Amplifier input 1dB gain compression	LNA gain = Hi			-15			dBm
IP3	Amplifier input third order intercept	f <sub>1</sub> - f <sub>2</sub> = 1MHz, LNA gain = Hi			-3			dBm
NF	Amplifier noise figure (50 $\Omega$ )	LNA gain = Hi		2.3	2.5	2.7		dB
LNA High C	Verload Mode		•		•		•	•
S <sub>21</sub>	Amplifier gain	LNA gain = Low		-14.0	-13.3	-12.0		dB
$\Delta S_{21}/\Delta T$	Gain temperature sensitivity	LNA gain = Low			-0.01			dB/°C
$\Delta S_{21}/\Delta V_{CC}$	Gain V <sub>CC</sub> drift	LNA gain = Low			0.3			dB/V
S <sub>12</sub>	Amplifier reverse isolation	LNA gain = Low			-16			dB
S <sub>11</sub>	Amplifier input match <sup>1</sup>	LNA gain = Low			-8			dB
S <sub>22</sub>	Amplifier output match <sup>1</sup>	LNA gain = Low			-8			dB
ISO	Isolation: LO <sub>1</sub> to LNA <sub>IN</sub>	LO mode = Hi, LNA gain = Low			-45			dB
P <sub>-1dB</sub>	Amplifier input 1dB gain compression	LNA gain = Low			+6			dBm
IP3	Amplifier input third order intercept	f <sub>1</sub> - f <sub>2</sub> = 1MHz, LNA gain = Low			17			dBm
NF	Amplifier noise figure (50Ω)	LNA gain = Low			17			dB
Rx Mixer (R	F = Pin 19, IF = Pins 5 and 6, LO = Pin	10 or 12, P <sub>LO</sub> = -10dBm)					•	•
PG <sub>C</sub>	Power conversion gain into $50\Omega$ : matched to $50\Omega$ using external balun circuitry.	f <sub>S</sub> = 2.45GHz, f <sub>LO</sub> = 2.1GHz, f <sub>IF</sub> = 350MHz		7.9	8.5	9.1		dB
$\Delta G_C / \Delta T$	Gain temperature drift				-0.016			dB/°C
$\Delta G_{C} / \Delta V_{CC}$	Gain V <sub>CC</sub> drift			1	0.34			dB/V
S <sub>11-RF</sub>	Input match at RF (2.45GHz) <sup>1</sup>				-15			dB
NF <sub>M</sub>	SSB noise figure (2.45GHz) (50 $\Omega$ )			10.2	10.9	11.6		dB
P <sub>-1dB</sub>	Mixer input 1dB gain compression			-11.4	-10.3	-9.2		dBm
IP3	Input third order intercept	f <sub>1</sub> - f <sub>2</sub> = 1MHz		1.7	2.8	3.9		dBm
f <sub>RF</sub>	RF frequency range <sup>3</sup>		2.4		2.45		2.5	GHz
f <sub>IF</sub>	IF frequency range <sup>3</sup>		300		350		400	MHz

### AC ELECTRICAL CHARACTERISTICS (continued)

SYMBOL	DADAMETER		LIMITS					
	PARAMETER	TEST CONDITIONS	MIN	<b>-4</b> σ	TYP	<b>+4</b> σ	MAX	UNITS
Rx Mixer Sp	ourious Components (P <sub>IN</sub> = P <sub>-1dB</sub> )	•	•	•	•		•	
P <sub>RF-IF</sub>	RF feedthrough to IF	C <sub>L</sub> = 2pF per side			-35			dBc
P <sub>LO-IF</sub>	LO feedthrough to IF	C <sub>L</sub> = 2pF per side	1		-35			dBc
Tx Mixer (R	F = Pin 19, IF = Pins 7 and 8, LO = Pin	10 or 12, P <sub>LO</sub> = -10dBm)	•	•	•			
PG <sub>C</sub>	Power conversion gain: $R_L = 50\Omega$ $R_S = 50\Omega$	$f_S = 2.45GHz,$ $f_{LO} = 2.1GHz,$ $f_{IF} = 350MHz$		15.0	17	19.9		dB
$\Delta G_C / \Delta T$	Gain temperature drift		1		-0.032			dB/°C
$\Delta G_C / \Delta V_{CC}$	Gain voltage drift				0.4			dB/V
S <sub>11-RF</sub>	Output match at RF (2.45GHz) <sup>1</sup>				-10			dB
NFM	SSB noise figure (2.45GHz) (50 $\Omega$ )				13.2			dB
P <sub>-1dB</sub>	Output 1dB gain compression			1.5	2.9	4.3		dBm
IP3	Output third order intercept	f <sub>1</sub> - f <sub>2</sub> = 1MHz		10.1	+11.5	12.9		dBm
f <sub>RF</sub>	RF frequency range <sup>3</sup>		2.4		2.45		2.5	GHz
f <sub>IF</sub>	IF frequency range <sup>3</sup>		300		350		400	MHz
Tx Mixer Sp	ourious Components (P <sub>OUT</sub> = P <sub>-1dB</sub> )	•	1				•	
P <sub>IF-RF</sub>	IF feedthrough to RF				-29			dBc
P <sub>LO-RF</sub>	LO feedthrough to RF				-20			dBc
P <sub>2LO-RF</sub>	2*LO feedthrough to RF				-25			dBc
P <sub>IMAGE-RF</sub>	Image feedthrough to RF				-0			dBc
LO Buffer:	Full and Half Frequency inputs	•		•			•	
P <sub>LO</sub>	LO drive level (see figure 16)		-10		-7		5	dBm
S <sub>11-LO1</sub>	Mixer input match (LO = 2.1GHz)	LO mode = Hi			-10			dB
S <sub>11-LO2</sub>	Mixer input match (LO = 1.05GHz)	LO mode = Low			-10			dB
f <sub>LO2G</sub>	LO2G frequency range <sup>3</sup>	LO mode = Hi	1.9		2.1		2.3	GHz
f <sub>LO1G</sub>	LO1G frequency range <sup>3</sup>	LO mode = Low	0.85		1.05		1.25	GHz
Switching <sup>2</sup>	•	•	•		-	-	-	•
t <sub>Rx-Tx</sub>	Receive-to-transmit switching time				1			μs
t <sub>Tx-Rx</sub>	Transmit-to-Receive switching time				1			μs
t <sub>POWER</sub> UP	Chip enable time				1			μs
t <sub>PWR</sub> DWN	Chip disable time			1	1		İ	μs

NOTES:

 With simple external matching
With 50pF coupling capacitors on all RF and IF parts
This part has been optimized for the frequency range at 2.4–2.5 GHz. Operation outside this frequency range may yield performance other than specified in this datasheet.

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### Low voltage RF transceiver — 2.45 GHz

Table 1. Truth Tab
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Chip-En	TxRx-SW	LNA-SW	LO-SW	Mode	LNA Gain	LO Freq. (Typ)
0	Х	Х	Х	Sleep	N/S	N/S
1	0	1	1	Receive	+14dB	2.1GHz
1	0	0	1	Receive	-8dB	2.1GHz
1	0	1	0	Receive	+14dB	1.05GHz
1	0	0	0	Receive	-8dB	1.05GHz
1	1	Х	1	Transmit	N/S	2.1GHz
1	1	Х	0	Transmit	N/S	1.05GHz

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#### **FUNCTIONAL DESCRIPTION**

The SA2420 is a 2.45GHz transceiver front-end available in the TSSOP-24 package. This integrated circuit (IC) consists of a low noise amplifier (LNA) and up- and down-converters. The injection of the local oscillator (LO) signal has two options: 1) direct injection of the LO signal at approximately 2GHz, or 2) injection of an LO signal at approximately 1GHz through an on-chip doubler. The SA2420 functions with a supply voltage range of 3 - 5 V (nominally). There is an enable/disable switch available to power up/down the entire chip in 1µs, typically. This transceiver has several unique features.

The LNA has two operating modes: 1) high gain mode with a gain = +14dB; and 2) low gain mode with a gain <-10dB. The switch for this option is internal and is controlled externally by high and low logic to the pin. When the LNA is switched into the attenuation mode, active matching circuitry (on-chip) is switched in (reducing the number of off-chip components required). To reduce power consumption when the chip is transmitting, the LNA is automatically switched into a "sleep" mode (internally) without the use of external circuitry.

The up and down frequency converters are single-ended at the RF port of the mixers. The up and down converters share the same

(RF) pin and use an internal switch for transmitting (up-converting) or receiving (down-converting) modes. The switch is controlled externally by high and low logic states. The RF port is matched to 50 $\Omega$  and has an input IP3 of +2.8dBm (mixer only). The down-convert mixer is buffered and has open collectors at the pins to allow for matching to common SAW filters. The up-convert mixer has differential inputs (IF port) and single-ended output (RF port), with an input pin to output pin gain of 17dB. The output of the up-converter is designed for a power level = +3dBm (P<sub>-1dB</sub>). The mixers are fed by the two LO options.

The available LO options are: direct injection (2.1GHz at the pin) or through an on-chip doubler. The doubler has a simple LC bandpass filter (internal) at its output which passes the second harmonic to the mixers. Through an internal switch (controlled externally), either LO can be used depending on the designer's application. If an application requires the use of a 1.05GHz VCO, then the doubler option would be used to double the frequency ( $2 \times 1.05$ GHz = 2.1GHz) before being injected into the mixers. For a 2.1GHz VCO, the direct option would be used. With this option, the signal passes through an on-chip buffer and is then injected into the mixers.



Figure 3. Rx & Tx Currents VS Temperature











Figure 6. LNA Gain &  $50\Omega$  NF VS Frequency



Figure 7. LNA Gain & 50  $\Omega$  NF VS Supply Voltage











Figure 10. LNA Input IP3 and P–1dB VS Frequency



Figure 11. LNA Loss Mode Input IP3 and P-1dB VS Voltage







Figure 13. Rx Mixer Conv. Gain & SSB NF VS Supply Voltage



Figure 14. Rx Mixer Input IP3 and P–1dB VS Supply Voltage



Figure 15. Rx Mixer Output IP3 and P–1dB VS Frequency



Figure 16. Rx Mixer Conversion Gain VS LO Power



Figure 17. Tx Mx conv. Gain and Output Pwr VS Temp.



Figure 18. Tx Mixer LO and Image Suppression



Figure 19. Tx Mixer Gain & NF VS Supply Voltage







Figure 21. Tx Mixer Output IP3 and P–1dB VS Temperature



Figure 22. Tx Mixer Output IP3 and P–1dB VS Frequency



Product specification



Figure 24. SA2420 RF Transciever



### SA2420

DEFINITIONS						
Data Sheet Identification	Product Status	Definition				
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.				
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.				
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